

Molecular electronics: connection across nano-sized electrode gaps

G. J. Ashwell, P. Wierzchowiec, C. J. Bartlett and P. D. Buckle

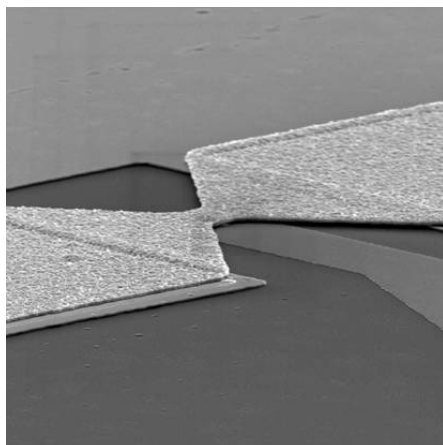


Fig. 1 SEM image of device

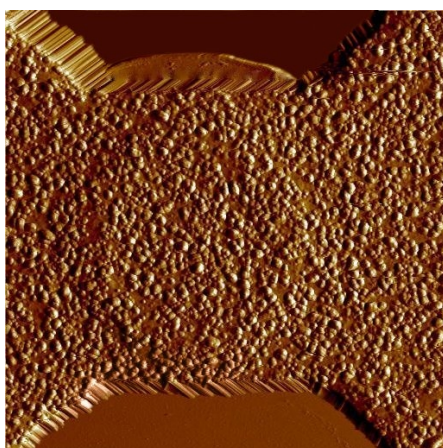
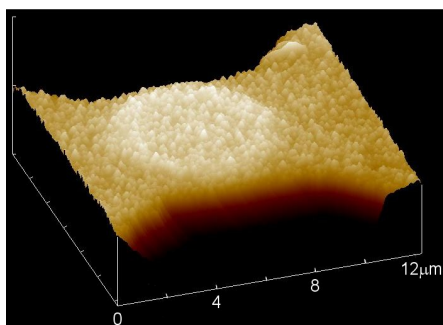


Fig. 2 AFM images of device.

Fig. 3 Stages of device fabrication: initial studies focused upon structures with just one connecting gold bridge to an adjacent pad (as shown below) but improved stability was obtained by using a double bridge as reported in the paper.

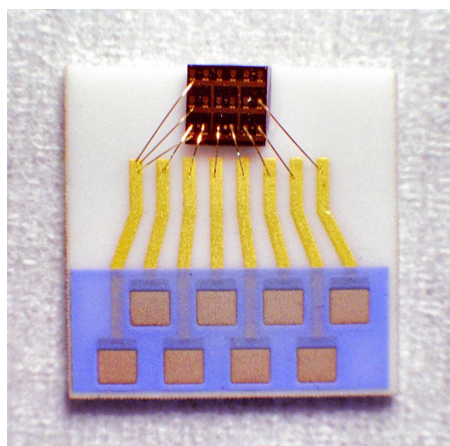
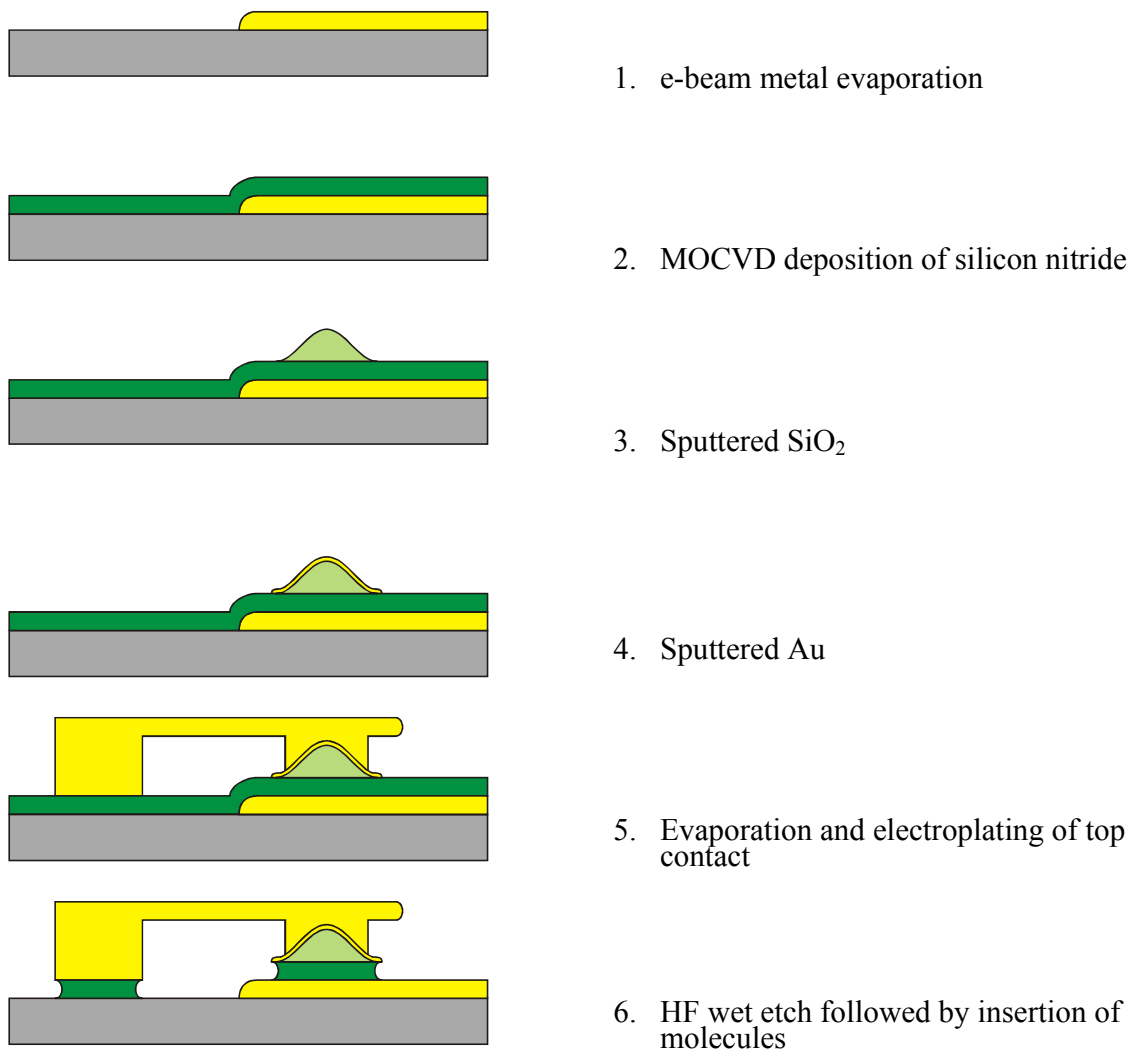


Fig. 4 Magnified image of eighteen devices on a silicon wafer with seven wires for electrical characterisation.